

A2
US1) entitled "COMBINATION POINT DESIGN FOR EFFICIENT THERMOELECTRIC COOLERS"
filed on December 7, 2000, and to co-pending U.S. Patent Application Serial No. 09/731,614
(IBM Docket No. AUS9-2000-0556-US1) entitled "ENHANCED INTERFACE
THERMOELECTRIC COOLERS USING ETCHED THERMOELECTRIC MATERIAL TIPS"
filed on December 7, 2000. The content of the above mentioned commonly assigned, co-pending
U. S. Patent applications are hereby incorporated herein by reference for all purposes.

IN THE CLAIMS:

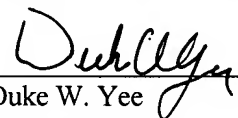
Please cancel claims 1-8.

REMARKS

Claims 1-8 have been canceled. Claims 9-27 remain in the application. These claims are believed to be in condition for allowance. The examiner is invited to call the undersigned at the below-listed telephone number if in the opinion of the examiner such a telephone conference would expedite or aid the prosecution and examination of this application.

Date: February 11, 2002

Respectfully submitted,


Duke W. Yee
Registration No. 34,285
CARSTENS YEE & CAHOON, LLP
P.O. Box 802334
Dallas, Texas 75380
(972) 367-2001
ATTORNEY FOR APPLICANT